

VERSION OF AMENDED CLAIMS TO SHOW CHANGES  
MADE THERETO

2. (Amended) An electrical attachment comprising:
- a module having [connection pads on] a bottom surface;
  - [a standoff, positioned on the bottom surface, having a height]
  - a printed circuit board [having connection pads];
  - a ball grid array, [interposing the connection pads of the module and the printed circuit board, wherein the height of the ball grid array is comparable to the height of the standoff] interposed between the bottom surface of the module and the printed circuit board;
  - a standoff, positioned on the bottom surface, having a height; wherein the standoff maintains the bottom surface of the module and the printed circuit board at the height of the standoff during reflow.

Before Reflow :

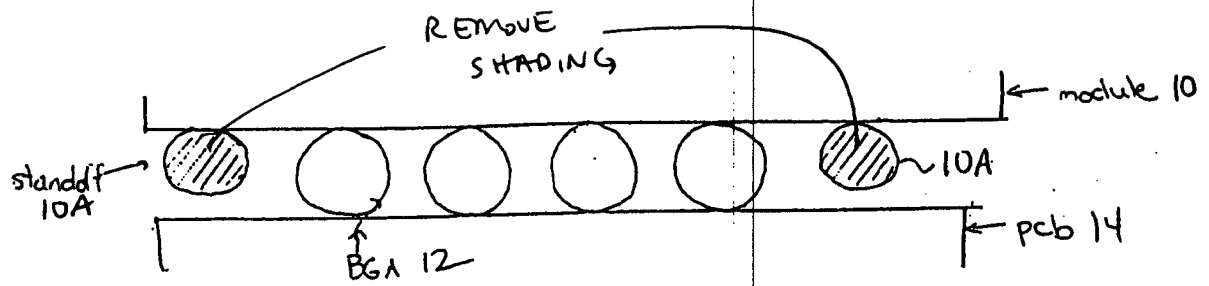


FIGURE 1A

Not approve  
+D  
6/10/02

After Reflow :

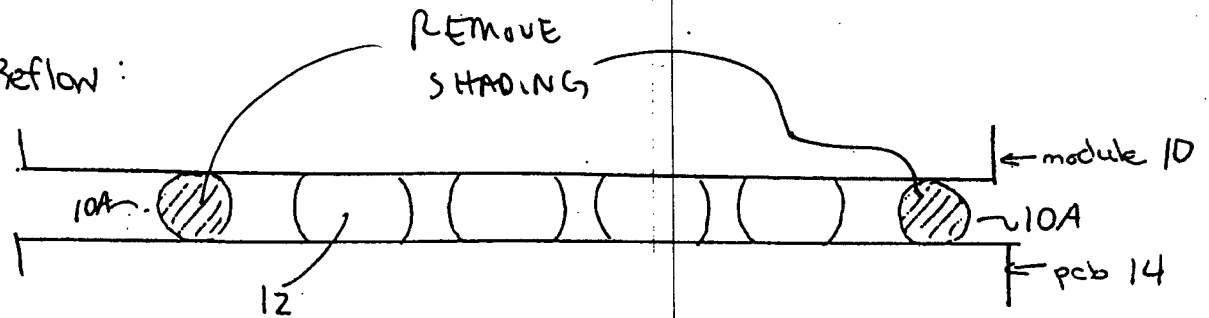


FIGURE 1B